



Quality Conformance and Qualification of Microelectronic Packages and Interconnects (Hardback)

By -

John Wiley & Sons Inc, United States, 1995. Hardback. Condition: New. Language: English. Brand new Book. All packaging engineers and technologists who want to ensure that they give their customers the highest quality, most cost-effective products should know that the paradigm has shifted. It has shifted away from the MIL-STDs and other government standards and test procedures that do not cost-effectively address potential failure mechanisms or the manufacturing processes of the product. It has shifted decisively towards tackling the root causes of failure and the appropriate implementation of cost-effective process controls, quality screens, and tests. This book's groundbreaking, science-based approach to developing qualification and quality assurance programs helps engineers reach a new level of reliability in today's high-performance microelectronics. It does this with powerful techniques for identifying and modeling failure mechanisms earlier in the design cycle, breaking the need to rely on field data and physics-of-failure product reliability assessment methods that can be proactively implemented throughout the design and manufacture of the product and process controls that decrease variabilities in the end product and reduce end-of-line screening and testing. A wide range of microelectronic package and interconnect configurations for both single- and multi-chip modules is examined, including chip and wire-bonds,...



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Reviews

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The book is great and fantastic. it absolutely was written very properly and beneficial. It is extremely difficult to leave it before concluding, once you begin to read the book.

-- **Lyda Davis II**